

QUADRUPLE 2-INPUT MULTIPLEXERS WITH STORAGE

SDLS174 – OCTOBER 1976 – REVISED MARCH 1988

- **Single-Rail Outputs on 'LS399**
- **Selects One of Two 4-Bit Data Sources and Stores Data Synchronously with System Clock**
- **Applications:**
 - Dual Source for Operands and Constants in Arithmetic Processor; Can Release Processor Register Files for Acquiring New Data**
 - Implement Separate Registers Capable of Parallel Exchange of Contents Yet Retain External Load Capability**
 - Universal Type Register for Implementing Various Shift Patterns: Even Has Compound Left-Right Capabilities**

description

This monolithic quadruple two-input multiplexer with storage provides essentially the equivalent functional capabilities of two separate MSI functions (SN54LS157/SN74LS157 and SN54LS175/SN74LS175) in a single 16-pin package.

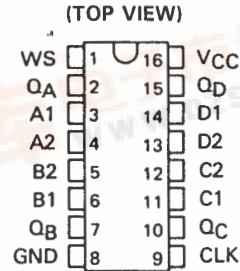
When the word-select input is low, word 1 (A1, B1, C1, D1) is applied to the flip-flops. A high input to word select will cause the selection of word 2 (A2, B2, C2, D2). The selected word is clocked to the output terminals on the positive-going edge of the clock pulse.

Typical power dissipation is 37 milliwatts. The SN54LS399 is characterized for operation over the full military range of -55°C to 125°C. The SN74LS399 is characterized for operation from 0°C to 70°C.

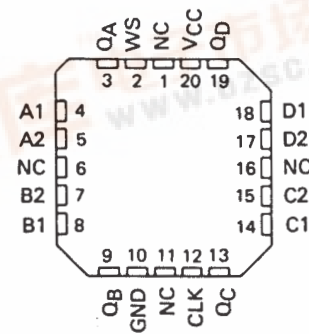
FUNCTION TABLE

| INPUTS | | OUTPUTS | | | |
|-------------|-------|-----------------|-----------------|-----------------|-----------------|
| WORD SELECT | CLOCK | Q _A | Q _B | Q _C | Q _D |
| L | ↑ | a1 | b1 | c1 | d1 |
| H | ↑ | a2 | b2 | c2 | d2 |
| X | L | Q _{A0} | Q _{B0} | Q _{C0} | Q _{D0} |

SN54LS399 . . . J OR W PACKAGE
SN74LS399 . . . D OR N PACKAGE

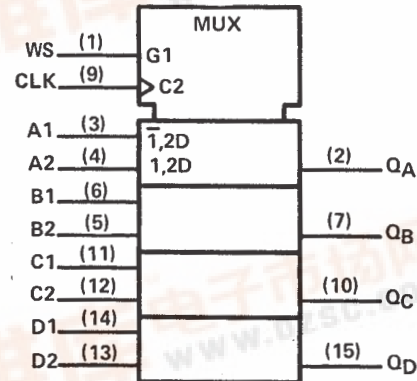


SN54LS399 . . . FK PACKAGE
(TOP VIEW)



NC - No internal connection

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.



SN54LS399, SN74LS399

QUADRUPLE 2-INPUT MULTIPLEXERS WITH STORAGE

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

| | |
|---|----------------|
| Supply voltage, V_{CC} (see Note 1) | 7 V |
| Input voltage | 7 V |
| Operating free-air temperature range: SN54LS399 | -55°C to 125°C |
| SN74LS399 | 0°C to 70°C |
| Storage temperature range | -65°C to 150°C |

NOTE 1: Voltage values are with respect to network ground terminals.

recommended operating conditions

| | SN54LS399 | | | SN74LS399 | | | UNIT |
|--|-------------|-----|------|-----------|-----|------|---------|
| | MIN | NOM | MAX | MIN | NOM | MAX | |
| Supply voltage, V_{CC} | 4.5 | 5 | 5.5 | 4.75 | 5 | 5.25 | V |
| High-level output current, I_{OH} | | | -400 | | | -400 | μ A |
| Low-level output current, I_{OL} | | | 4 | | | 8 | mA |
| Width of clock pulse, high or low level, t_W | 20 | | | 20 | | | ns |
| Setup time, t_{SU} | Data | 25 | | 25 | | | ns |
| | Word select | 45 | | 45 | | | |
| Hold time, t_H | Data | 0 | | 0 | | | ns |
| | Word select | 0 | | 0 | | | |
| Operating free-air temperature, T_A | -55 | | 125 | 0 | | 70 | °C |

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS† | SN54LS399 | | | SN74LS399 | | | UNIT |
|--|---|-------------------------|------|------|-----------|------|------|---------|
| | | MIN | TYP‡ | MAX | MIN | TYP‡ | MAX | |
| V_{IH} High-level input voltage | | 2 | | | 2 | | | V |
| V_{IL} Low-level input voltage | | | | 0.7 | | | 0.8 | V |
| V_{IK} Input clamp voltage | $V_{CC} = \text{MIN}, I_I = -18 \text{ mA}$ | | | -1.5 | | | -1.5 | V |
| V_{OH} High-level output voltage | $V_{CC} = \text{MIN}, V_{IH} = 2 \text{ V}, V_{IL} = V_{IL \text{ max}}, I_{OH} = -400 \mu\text{A}$ | 2.5 | 3.4 | | 2.7 | 3.4 | | V |
| V_{OL} Low-level output voltage | $V_{CC} = \text{MIN}, V_{IH} = 2 \text{ V}, V_{IL} = V_{IL \text{ max}}$ | $I_{OL} = 4 \text{ mA}$ | | 0.25 | 0.4 | 0.25 | 0.4 | V |
| | | $I_{OL} = 8 \text{ mA}$ | | | | 0.35 | 0.5 | |
| I_I Input current at maximum input voltage | $V_{CC} = \text{MAX}, V_I = 7 \text{ V}$ | | | 0.1 | | | 0.1 | mA |
| I_{IH} High-level input current | $V_{CC} = \text{MAX}, V_I = 2.7 \text{ V}$ | | | 20 | | | 20 | μ A |
| I_{IL} Low-level input current | $V_{CC} = \text{MAX}, V_I = 0.4 \text{ V}$ | | | -0.4 | | | -0.4 | mA |
| I_{OS} Short-circuit output current§ | $V_{CC} = \text{MAX}$ | -20 | | -100 | -20 | | -100 | mA |
| I_{CC} Supply current | $V_{CC} = \text{MAX},$ See Note 2 | | 7.3 | 13 | | 7.3 | 13 | mA |

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at $V_{CC} = 5 \text{ V}, T_A = 25^\circ\text{C}$.

§ Not more than one output should be shorted at a time, duration of the short-circuit should not exceed one second.

NOTE 2: With all outputs open and all inputs except clock low, I_{CC} is measured after applying a momentary 4.5 V, followed by ground, to the clock input.

switching characteristics, $V_{CC} = 5 \text{ V}, T_A = 25^\circ\text{C}$

| PARAMETER | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|--|---|-----|-----|-----|------|
| t_{PLH} Propagation delay time, low-to-high-level output | $C_L = 15 \text{ pF}, R_L = 2 \text{ k}\Omega,$ See Note 3 | | 18 | 27 | ns |
| t_{PHL} Propagation delay time, high-to-low-level output | | | 21 | 32 | |

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

PACKAGING INFORMATION

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/Ball Finish | MSL Peak Temp ⁽³⁾ |
|------------------|-----------------------|--------------|-----------------|------|-------------|-------------------------|------------------|------------------------------|
| 84154012A | ACTIVE | LCCC | FK | 20 | 1 | TBD | Call TI | Level-NC-NC-NC |
| 8415401EA | ACTIVE | CDIP | J | 16 | 1 | TBD | Call TI | Level-NC-NC-NC |
| 8415401EA | ACTIVE | CDIP | J | 16 | 1 | TBD | Call TI | Level-NC-NC-NC |
| 8415401FA | ACTIVE | CFP | W | 16 | 1 | TBD | Call TI | Level-NC-NC-NC |
| 8415401FA | ACTIVE | CFP | W | 16 | 1 | TBD | Call TI | Level-NC-NC-NC |
| SN54LS399J | ACTIVE | CDIP | J | 16 | 1 | TBD | Call TI | Level-NC-NC-NC |
| SN54LS399J | ACTIVE | CDIP | J | 16 | 1 | TBD | Call TI | Level-NC-NC-NC |
| SN74LS399D | ACTIVE | SOIC | D | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS399D | ACTIVE | SOIC | D | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS399DE4 | ACTIVE | SOIC | D | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS399DE4 | ACTIVE | SOIC | D | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS399DR | OBSOLETE | SOIC | D | 16 | | TBD | Call TI | Call TI |
| SN74LS399DR | OBSOLETE | SOIC | D | 16 | | TBD | Call TI | Call TI |
| SN74LS399N | ACTIVE | PDIP | N | 16 | 25 | Pb-Free (RoHS) | CU NIPDAU | Level-NC-NC-NC |
| SN74LS399N | ACTIVE | PDIP | N | 16 | 25 | Pb-Free (RoHS) | CU NIPDAU | Level-NC-NC-NC |
| SN74LS399N3 | OBSOLETE | PDIP | N | 16 | | TBD | Call TI | Call TI |
| SN74LS399N3 | OBSOLETE | PDIP | N | 16 | | TBD | Call TI | Call TI |
| SN74LS399NE4 | ACTIVE | PDIP | N | 16 | 25 | Pb-Free (RoHS) | CU NIPDAU | Level-NC-NC-NC |
| SN74LS399NE4 | ACTIVE | PDIP | N | 16 | 25 | Pb-Free (RoHS) | CU NIPDAU | Level-NC-NC-NC |
| SN74LS399NSR | ACTIVE | SO | NS | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS399NSR | ACTIVE | SO | NS | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS399NSRE4 | ACTIVE | SO | NS | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS399NSRE4 | ACTIVE | SO | NS | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SNJ54LS399FK | ACTIVE | LCCC | FK | 20 | 1 | TBD | Call TI | Level-NC-NC-NC |
| SNJ54LS399FK | ACTIVE | LCCC | FK | 20 | 1 | TBD | Call TI | Level-NC-NC-NC |
| SNJ54LS399J | ACTIVE | CDIP | J | 16 | 1 | TBD | Call TI | Level-NC-NC-NC |
| SNJ54LS399J | ACTIVE | CDIP | J | 16 | 1 | TBD | Call TI | Level-NC-NC-NC |
| SNJ54LS399W | ACTIVE | CFP | W | 16 | 1 | TBD | Call TI | Level-NC-NC-NC |
| SNJ54LS399W | ACTIVE | CFP | W | 16 | 1 | TBD | Call TI | Level-NC-NC-NC |

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

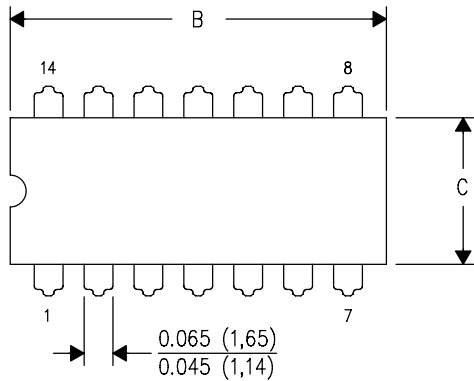
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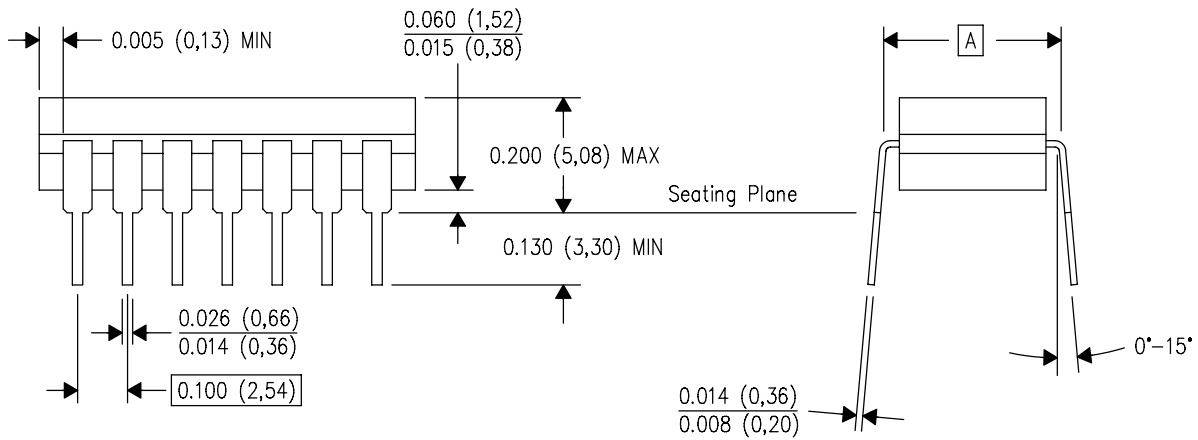
J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



| DIM \ PINS ** | 14 | 16 | 18 | 20 |
|---------------|------------------------|------------------------|------------------------|------------------------|
| A | 0.300 (7,62) BSC | 0.300 (7,62) BSC | 0.300 (7,62) BSC | 0.300 (7,62) BSC |
| B MAX | 0.785 (19,94) | .840 (21,34) | 0.960 (24,38) | 1.060 (26,92) |
| B MIN | — | — | — | — |
| C MAX | 0.300 (7,62) | 0.300 (7,62) | 0.310 (7,87) | 0.300 (7,62) |
| C MIN | 0.245 (6,22) | 0.245 (6,22) | 0.220 (5,59) | 0.245 (6,22) |



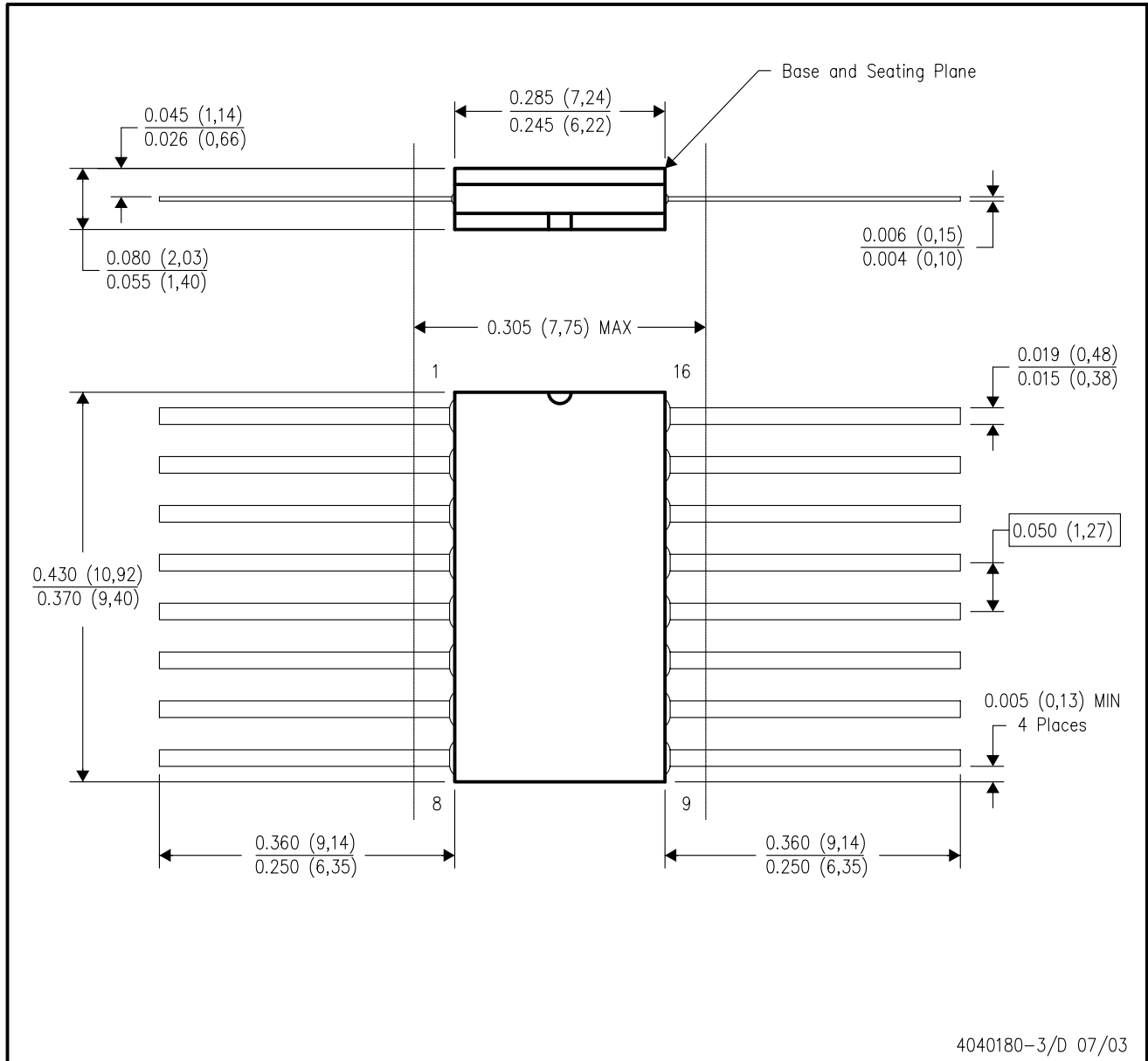
4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

MECHANICAL DATA

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only.
 - Falls within MIL STD 1835 GDFP1-F16 and JEDEC MO-092AC

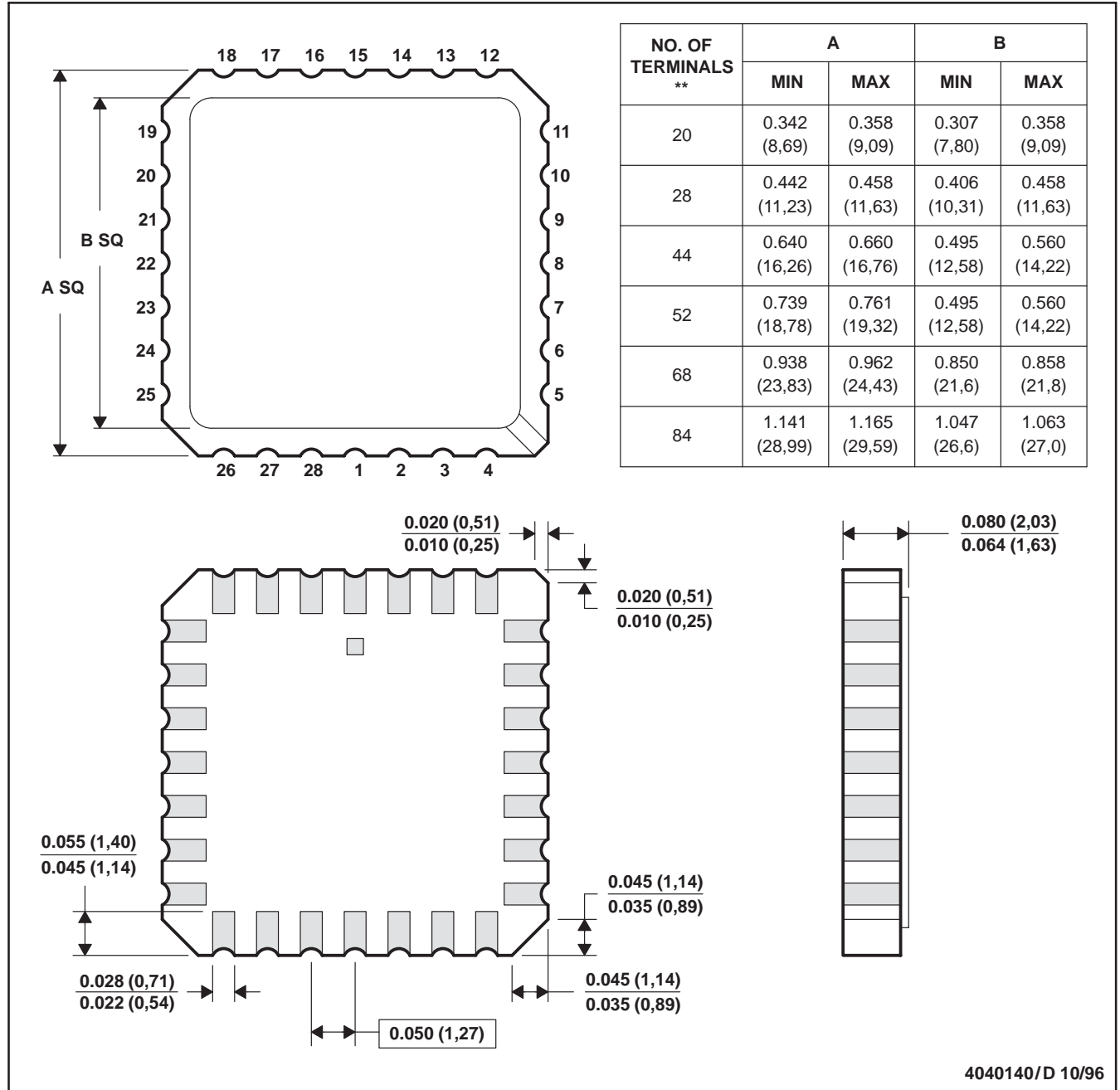
MECHANICAL DATA

MLCC006B – OCTOBER 1996

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



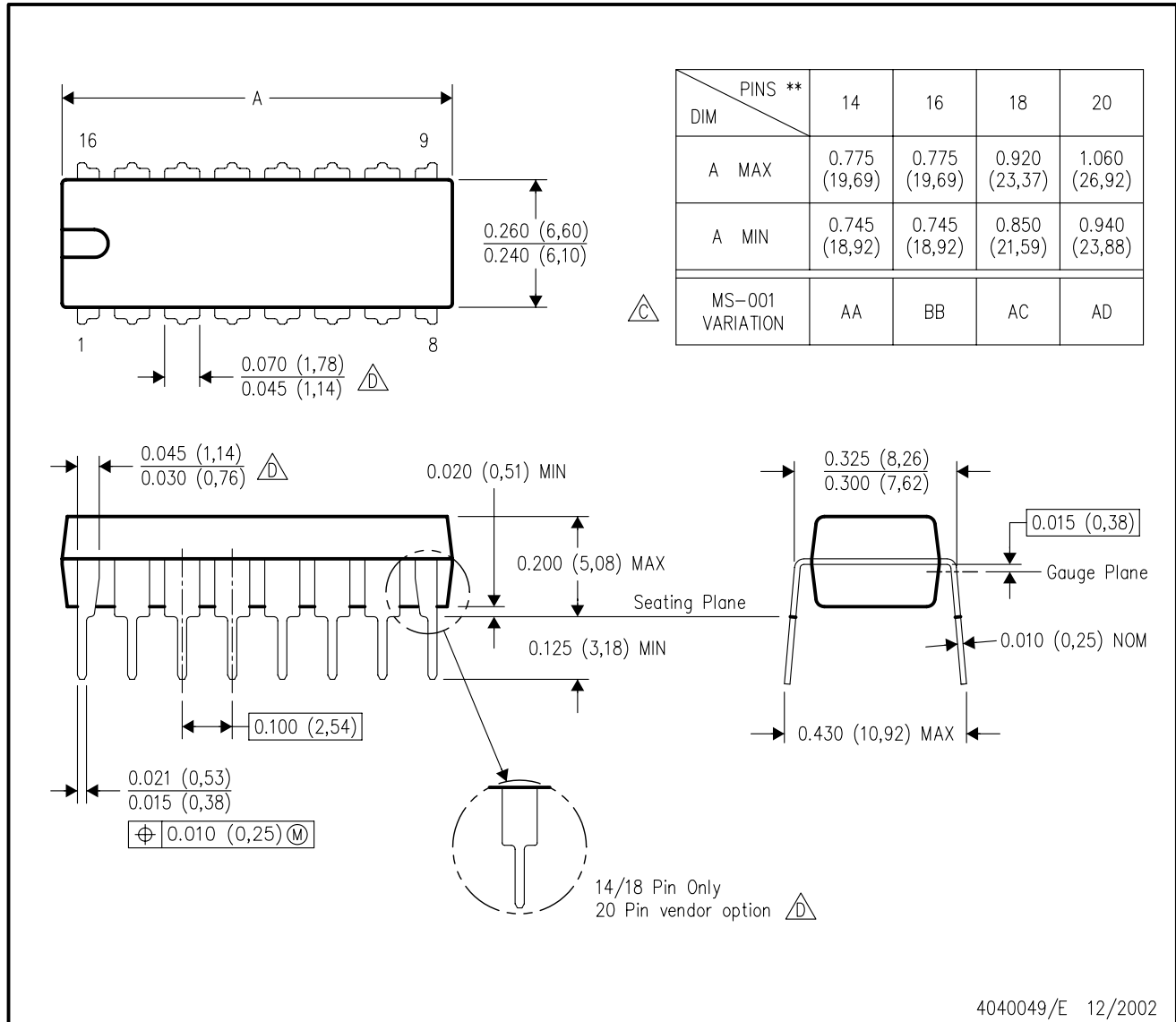
- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a metal lid.
 - The terminals are gold plated.
 - Falls within JEDEC MS-004

MECHANICAL DATA

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



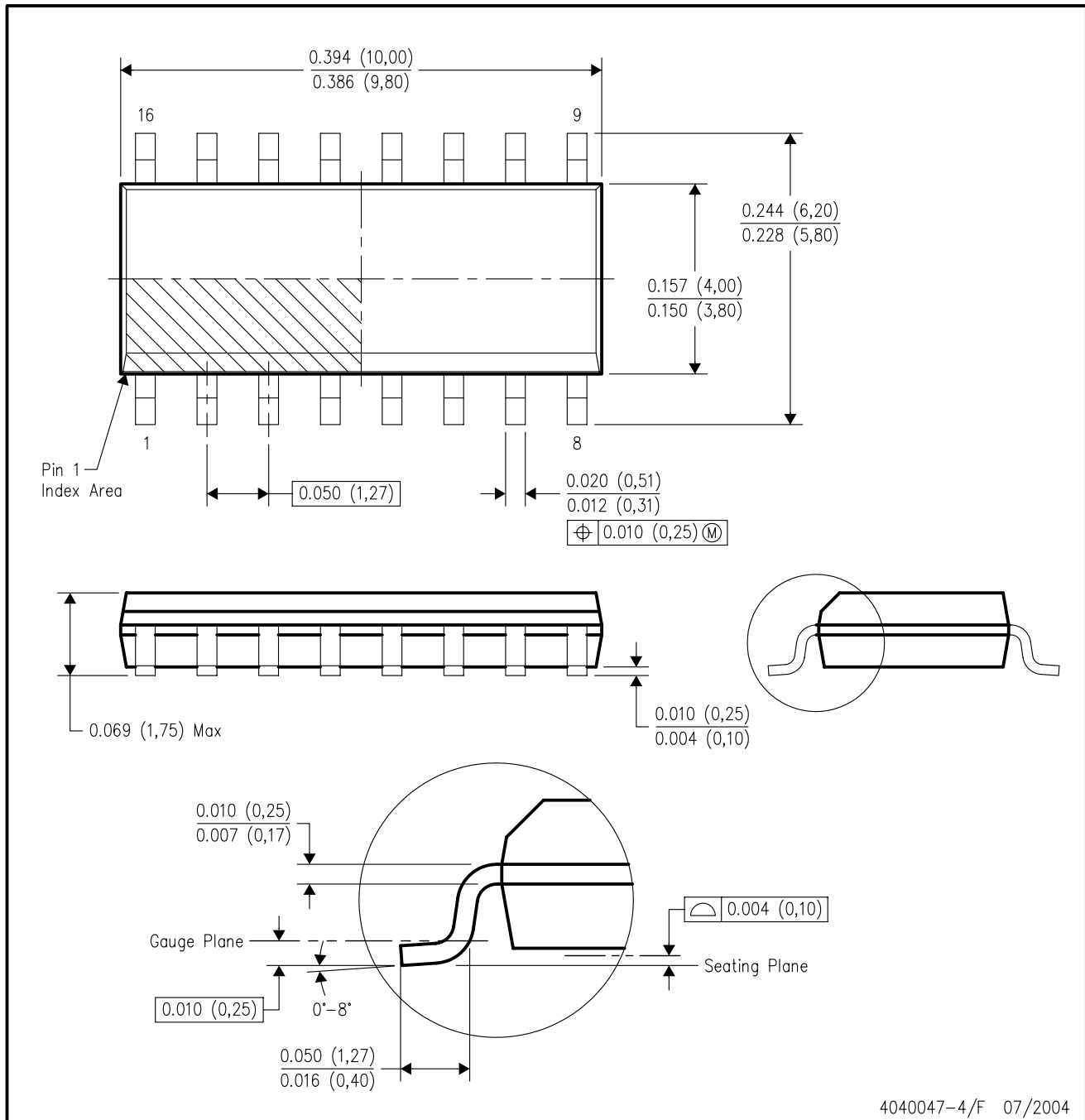
4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

MECHANICAL DATA

D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



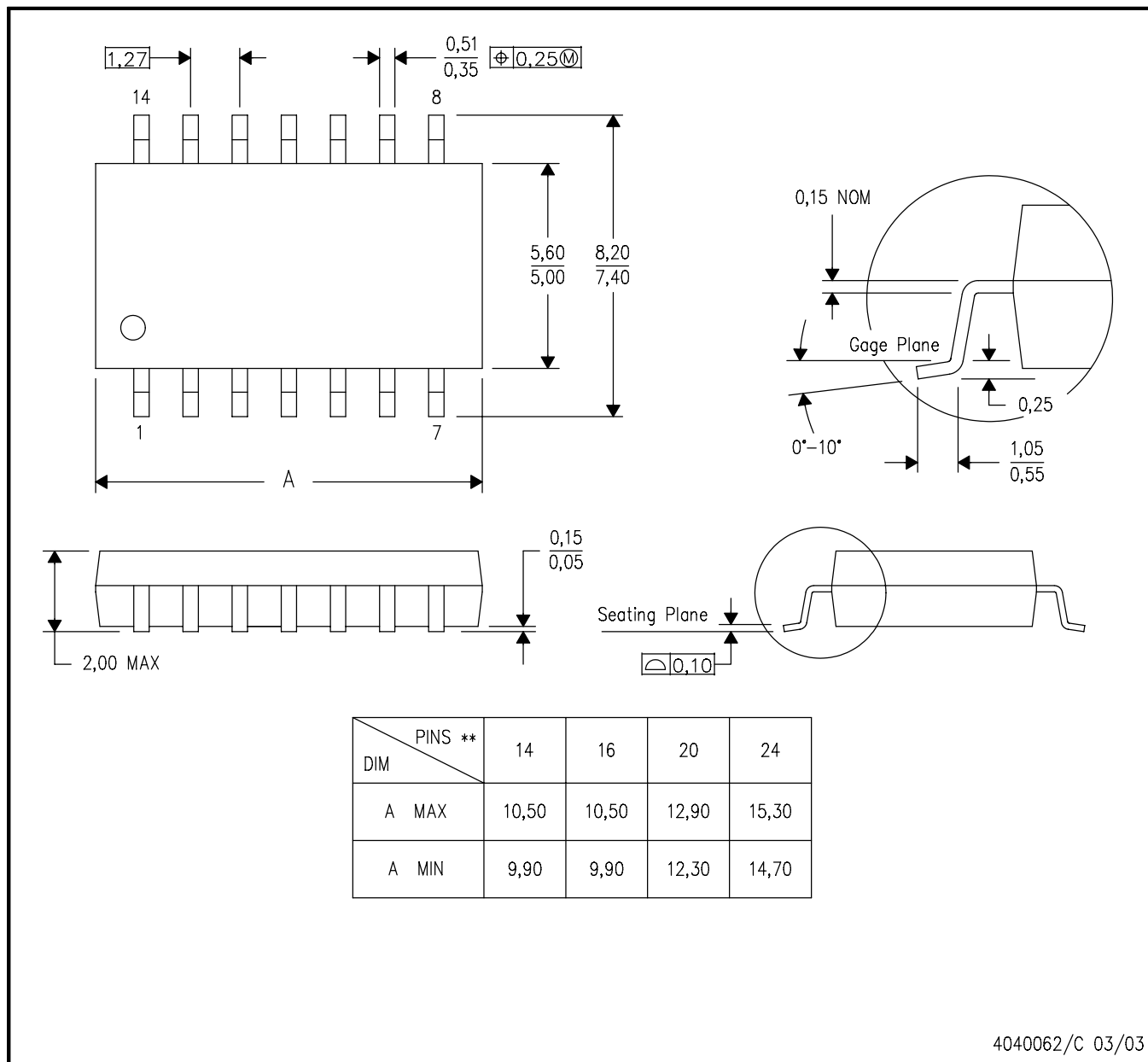
- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - Falls within JEDEC MS-012 variation AC.

MECHANICAL DATA

NS (R-PDSO-G)**

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



4040062/C 03/03

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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